

**REMARKS**

Claims 1-20 are present in this application. Claims 9-17 and 19 remain withdrawn for being directed to a non-elected invention and Applicants reserve the right to file a divisional application directed to the non-elected invention including at least claims 9-17 and 19. Clarifying amendments have been made to claims 1 and 18. Support for these amendments are found throughout the present application and in particular on pages 5, 6 and 13-15 of the present specification. Reconsideration and allowance of claims 1-8, 18 and 20 of the present application as amended are earnestly solicited in view of the following remarks.

The drawings stands objected under 37 CFR § 1.83(a). It continues to be alleged that the drawings fail to show a resonant cavity, magnetron source, magnetic flux with a spiral copper antenna, power supply and a ceramic chuck as described in the present specification. However, these elements are conventional features that are disclosed but not claimed in the present application. These elements are described in the present specification to provide the environment for the present invention and are not essential for fully understanding the claimed invention and a detailed illustration of these unclaimed features is not essential for a proper understanding of the present invention as 37 CFR § 1.83(a) only requires that every feature of the invention specified in the claims be shown in the drawings. Accordingly, it is respectfully submitted that the drawings provide for a proper understanding of the claimed invention and proposed drawing corrections are not necessary. Therefore, it is respectfully requested that the objection to the drawings be reconsidered and withdrawn

Claims 1, 2, 5-8, 18 and 20 stand rejected under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 6,066,547 to Maekawa and claims 3 and 4 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Maekawa. These rejections are respectfully traversed.

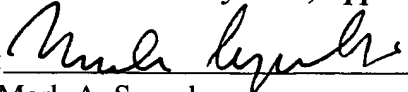
Claims 1 and 18 of the present application have been amended to recite that the method for annealing and processing a semiconductor structure cures defects of the semiconductor structure, activates the dopant material, repairs the lattice structure and minimizes the as implanted junction depth and the post annealing junction depth of the dopant material by the combination of subjecting the semiconductor to electromagnetic

fields or athermal heating and applying a LTRTA process to the semiconductor structure. Maekawa is relied upon to disclose a method for annealing amorphous silicon films to produce polycrystalline films suitable for thin film transistors fabricated on glass substrates and annealing a silicon film and nickel film structure are annealed for a short duration, less than 30 seconds to minimize the penetration of nickel into the dielectric material as the inclusion of nickel in the dielectric material degrades the electrical isolating function of the dielectric. However, Maekawa does not disclose the combination of subjecting the semiconductor structure to an oscillating field or athermal heating and applying a LTRTA process thereto as recited in claims 1 and 18 of the present application. As a result, Maekawa does not suggest or imply a method for curing structural defects, activating the dopant material, repairing the lattice structure and minimizing differences between the as-implanted junction depth and the post annealing junction depth as recited in claims 1 and 18 of the present application. Accordingly, it is respectfully submitted that claims 1 and 18 along with their dependent claims 2-8 and 20 patentably define over Maekawa for at least the reasons set forth above and it is respectfully requested that these rejections be reconsidered and withdrawn.

In view of these amendments and for all of the above stated reasons, it is respectfully submitted that all of the outstanding objections and rejections have been overcome. Therefore, it is respectfully requested that claims 1-8, 18 and 20 of the present application be passed to issue.

If any issues remain unresolved, the Examiner is requested to telephone the undersigned attorney. Please charge any additional fees or credit any overpayments to deposit account No. 50-0896.

Respectfully submitted,  
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